Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights resonant international and Pan-American copyright conventions.			all rights reserved untions.	nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assemblevel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering response.						ssembly with loweresponsibility.				
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier	Information														
Company	name*	Company unique ID			1	Unique ID Authority					Response Date*				
nsemi											2025-06-07				
Contact N	ame	Title - Contact			1	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	d Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Da	Effective Date Version Manufacturing S		ring Site	Weight*		UOM	Unit Type	
		2SB1201	S-E	BIP PNP 2A 50V			2025-06-07	2025-06-07 CNG			325.75		mg	Each	
Ianufa	cturing Proccess Informat	ion												,	
	Terminal Plating / Grid Array Material T		Cerminal Base Alloy J-STD-0		-STD-020 MSL	Rating	Peak Process Body Temperat		ture Max Time at Peak Temper		Temperati	ire Numl	ber of Reflow Cyc	eles	
contains Bi		CU Alloy NA		NA		0 C		30 seco		secono	ds 3				
omments															
or more	information regarding material	composition j	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.33	mg	Supplier	Silicon (Si)	7440-21-3		0.33	mg
Die Attach Solder	0.15	mg	Supplier	Silver (Ag)	7440-22-4		0.0038	mg
			A	Lead (Pb)	7439-92-1	7a	0.1388	mg
			Supplier	Tin (Sn)	7440-31-5		0.0075	mg
Lead Frame	191.37	mg	Supplier	Silver (Ag)	7440-22-4		0.3827	mg
			Supplier	Tin (Sn)	7440-31-5		0.2679	mg
			Supplier	Copper (Cu)	7440-50-8		190.7193	mg
Mold Compound-Black	130.38	mg		Brominated epoxy resin	proprietary data		1.8253	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		5.8671	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.1734	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3038	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		97.785	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		22.1646	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2608	mg
Plating	3.34	mg	В	Bismuth (Bi)	7440-69-9		0.02	mg
			Supplier	Tin (Sn)	7440-31-5		3.32	mg
Wire Bond - Au	0.18	mg	Supplier	Gold (Au)	7440-57-5		0.18	mg